



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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LOCTITE 384

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PRODUCT DESCRIPTION

LOCTITE 384 provides the following product characteristics:

| | |
|----------------------|---|
| Technology | Acrylic |
| Chemical Type | Modified acrylic |
| Appearance (uncured) | White to off-white paste ^{LMS} |
| Components | One component - requires no mixing |
| Viscosity | High |
| Cure | Activator |
| Cure Benefit | Room temperature cure |
| Application | Bonding |
| Strength | Medium |

LOCTITE 384 is a thermally conductive adhesive system designed for bonding heat generating components to heat sinks. The high thermal conductivity provides excellent heat dissipation for thermally sensitive components, while the controlled strength permits field and service repair. In high pot applications this product should be limited to a maximum of 500 volts. Typical applications include bonding transformers, transistors and other heat generating electronic components to printed circuit board assemblies or heat sinks.

TYPICAL PROPERTIES OF UNCURED MATERIAL

| | |
|---|-------------------------------------|
| Specific Gravity @ 25 °C | 1.64 |
| Flash Point - See SDS | |
| Viscosity, Brookfield - HBT, 25 °C, mPa·s (cP): | |
| Spindle TE, speed 2.5 rpm, Helipath | 500,000 to 2,250,000 ^{LMS} |
| Spindle TE, speed 20 rpm, Helipath | 300,000 to 800,000 ^{LMS} |

TYPICAL PROPERTIES OF CURED MATERIAL

Physical Properties

| | |
|--|--|
| Coefficient of Thermal Expansion, ISO 11359-2, K ⁻¹ | 69×10 ⁻⁶ |
| Coefficient of Thermal Conductivity, ISO 8302, W/(m·K) | 0.757 |
| Elongation, at break, ISO 527-3, % | 0.9 |
| Tensile Strength, at break, ISO 527-3 | N/mm ² 13 (psi) (1,800) |
| Young's Modulus | N/mm ² 2,800 (psi) (400,000) |

Electrical Properties

| | |
|--|----------------------|
| Volume Resistivity, IEC 60093, Ω·cm | 1.3×10 ¹² |
| Surface Resistivity, IEC 60093, Ω | 5.1×10 ¹³ |
| Dielectric Breakdown Strength, IEC 60243-1, kV/mm | 26.7 |
| Dielectric Constant / Dissipation Factor, IEC 60250: | |
| 100 Hz | 6.48 / 0.1 |
| 1 kHz | 5.86 / 0.04 |
| 1 MHz | 5.22 / 0.03 |

TYPICAL PERFORMANCE OF CURED MATERIAL

Adhesive Properties

| | |
|---|--|
| Cured for 24 hours @ 22 °C, Activator 7387™ on 1 side | |
| Lap Shear Strength, ISO 4587: | |
| Steel | N/mm ² ≥5.2 (psi) (≥754) |

TYPICAL ENVIRONMENTAL RESISTANCE

| | |
|---|--|
| Cured for 72 hours @ 22 °C, Activator 7387™ on 1 side | |
| Shear Strength | |
| Lap Shear Strength, ISO 4587: | |
| Steel | N/mm ² ≥5.2 (psi) (≥754) |

Chemical/Solvent Resistance

Aged under conditions indicated and tested @ 22 °C.

| Environment | °C | % of initial strength |
|-------------|----|-----------------------|
| | | 720 h |
| Air | 87 | 140 |
| Water | 87 | 75 |
| Freon TF | 87 | 85 |

Thermal Cycle Resistance

Bonded aluminum to epoxyglass lapshears cured 72 hours using Activator 7387™ on 1 side were subjected to thermal cycling of 15°C to 100°C with a ramp time of 30 minutes. No loss in strength occurred after 1,000 hours of cycle time.

GENERAL INFORMATION

For safe handling information on this product, consult the Safety Data Sheet (SDS).

Directions for use:

- For best performance bond surfaces should be clean and free from grease.
- Use applicator to apply the activator to the surface to be bonded.
- After the solvent evaporates, the active ingredients will appear wet, and will remain active for up to 2 hours after application. Contamination of the surface before bonding should be prevented.
- Apply adhesive to the unactivated surface.
- Secure the assembly, and wait for the adhesive to fixture (approximately 5 minutes) before any further handling. Full cure occurs in 4 - 24 hours.
- The amount of adhesive applied to the part or heat sink should be limited to the amount necessary to fill the bond and just enough to give a small fillet.
- The dispensing or application of the adhesive should be done as to minimize air entrapment within the bondline.

8. The successful application of this product depends on accurate dispensing on the parts to be bonded. Loctite Equipment Engineers are available to assist you in selecting and implementing the appropriate dispensing equipment for your application.

Device Removal/Repair

Components or devices bonded with LOCTITE 384 can be removed while hot using heat from a hot air jet. Bond strength decreases at approximately 65 °C to 93 °C allowing components to be removed with lower shear forces. Method of removal/repair should be specifically determined due to the variety of components or devices bonding behavior.

Loctite Material Specification^{LMS}

LMS dated October 24, 2003. Test reports for each batch are available for the indicated properties. LMS test reports include selected QC test parameters considered appropriate to specifications for customer use. Additionally, comprehensive controls are in place to assure product quality and consistency. Special customer specification requirements may be coordinated through Henkel Quality.

Storage

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage: 2 °C to 8 °C. Storage below 2 °C or greater than 8 °C can adversely affect product properties. Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

Conversions

$(^{\circ}\text{C} \times 1.8) + 32 = ^{\circ}\text{F}$
 $\text{kV/mm} \times 25.4 = \text{V/mil}$
 $\text{mm} / 25.4 = \text{inches}$
 $\mu\text{m} / 25.4 = \text{mil}$
 $\text{N} \times 0.225 = \text{lb}$
 $\text{N/mm} \times 5.71 = \text{lb/in}$
 $\text{N/mm}^2 \times 145 = \text{psi}$
 $\text{MPa} \times 145 = \text{psi}$
 $\text{N}\cdot\text{m} \times 8.851 = \text{lb}\cdot\text{in}$
 $\text{N}\cdot\text{m} \times 0.738 = \text{lb}\cdot\text{ft}$
 $\text{N}\cdot\text{mm} \times 0.142 = \text{oz}\cdot\text{in}$
 $\text{mPa}\cdot\text{s} = \text{cP}$

Note:

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. The product can have a variety of different applications as well as differing application and working conditions in your environment that are beyond our control. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

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Reference 1.3